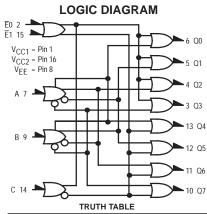
Binary to 1-8 Decoder (Low)

The MC10H161 provides parallel decoding of a three bit binary word to one of eight lines. The MC10H161 is useful in high–speed multiplexer/demultiplexer applications.

The MC10H161 is designed to decode a three bit input word to one of eight output lines. The MC10H161 output will be low when selected while all other output are high. The enable inputs, when either or both are high, force all outputs high.

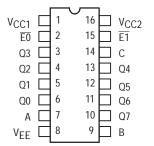
The MC10H161 is a true parallel decoder. This eliminates unequal parallel path delay times found in other decoder designs. These devices are ideally suited for multiplexer/demultiplexer applications.

- Propagation Delay, 1.0 ns Typical
- Power Dissipation, 315 mW Typical (same as MECL 10K)
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K-Compatible



ENABLE INPUTS INPUTS			OUTPUTS									
Ē1	Ē0	С	В	Α	Q0	Q1	Q2	Q3	Q4	Q5	Q6	Q7
L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н
L	L	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н
L	L	L	Н	L	Н	Н	L	Н	Н	Н	Н	Н
L	L	L	Н	Н	Н	Н	Н	L	Н	Н	Н	Н
L	L	Н	L	L	Н	Н	Н	Н	L	Н	Н	Н
L	L	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н
L	L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	Н
L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L
Н	Х	Х	Х	Х	Н	Н	Н	Н	Н	Н	Н	Н
X	Н	Х	Х	Х	Н	Н	Н	Н	Н	Н	Н	Н

DIP PIN ASSIGNMENT



Pin assignment is for Dual-in-Line Package. For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



ON Semiconductor

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MARKING DIAGRAMS



CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10H161L	CDIP-16	25 Units/Rail
MC10H161P	PDIP-16	25 Units/Rail
MC10H161FN	PLCC-20	46 Units/Rail

MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
VEE	Power Supply (V _{CC} = 0)	-8.0 to 0	Vdc
VI	Input Voltage (V _{CC} = 0)	0 to VEE	Vdc
l _{out}	Output Current – Continuous – Surge	50 100	mA
TA	Operating Temperature Range	0 to +75	°C
T _{stg}	Storage Temperature Range – Plastic – Ceramic	−55 to +150 −55 to +165	°C °C

ELECTRICAL CHARACTERISTICS ($V_{\mbox{EE}}$ = -5.2 V ±5%) (See Note 1.)

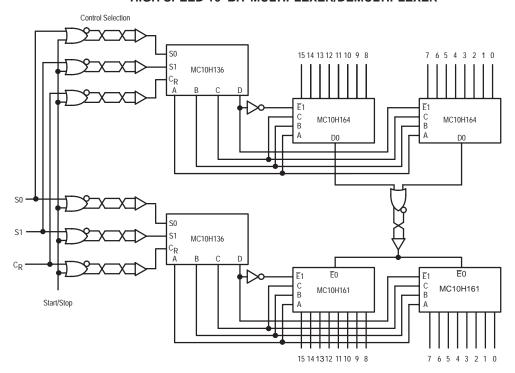
		0)°	25°		75°		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
ΙE	Power Supply Current	_	84	-	76	-	84	mA
linH	Input Current High	_	465	-	275	-	275	μΑ
linL	Input Current Low	0.5	_	0.5	_	0.3	_	μΑ
Voн	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
VOL	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
VIH	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
VIL	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

AC PARAMETERS

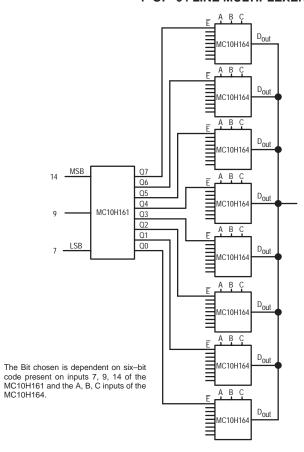
tpd	Propagation Delay							ns
'	Data	0.6	2.0	0.65	2.1	0.7	2.2	
	Enable	8.0	2.3	8.0	2.4	0.9	2.5	
t _r	Rise Time	0.55	1.7	0.65	1.8	0.7	1.9	ns
t _f	Fall Time	0.55	1.7	0.65	1.8	0.7	1.9	ns

^{1.} Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50–ohm resistor to –2.0 volts.

TYPICAL APPLICATIONS HIGH SPEED 16-BIT MULTIPLEXER/DEMULTIPLEXER



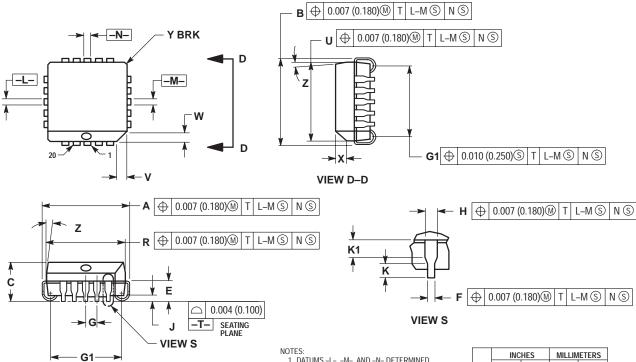
1-OF-64 LINE MULTIPLEXER



PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



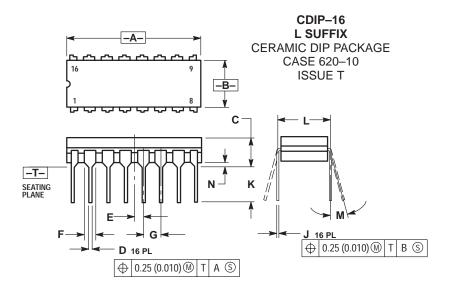
⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

- DATUMS -L-, -M-, AND -N- DETERMINED
 WHERE TOP OF LEAD SHOULDER EXITS PLASTIC WILLY LOVE LEAD STOUDER EXTENSIVE SOLUTION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 4. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH.
- 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIMETERS				
DIM	MIN	MAX	MIN	MAX			
Α	0.385	0.395	9.78	10.03			
В	0.385	0.395	9.78	10.03			
С	0.165	0.180	4.20	4.57			
Ε	0.090	0.110	2.29	2.79			
F	0.013	0.019	0.33	0.48			
G	0.050	BSC	1.27 BSC				
Н	0.026	0.032	0.66	0.81			
J	0.020		0.51				
K	0.025		0.64				
R	0.350	0.356	8.89	9.04			
U	0.350	0.356	8.89	9.04			
٧	0.042	0.048	1.07	1.21			
W	0.042	0.048	1.07	1.21			
Х	0.042	0.056	1.07	1.42			
Υ		0.020		0.50			
Z	2°	10 °	2 °	10 °			
G1	0.310	0.330	7.88	8.38			
K1	0.040		1.02				

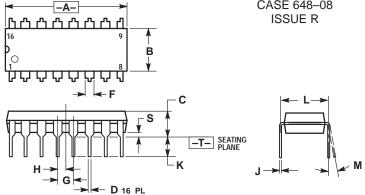
PACKAGE DIMENSIONS



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	A 0.750 0.785		19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.015 0.020		0.50	
Ε	0.050	0.050 BSC		BSC	
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300 BSC		7.62	BSC	
M	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08



⊕ 0.25 (0.010) M T A M

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.740	0.770	18.80	19.55		
В	B 0.250 0.270		6.35	6.85		
С	C 0.145 0.1		3.69	4.44		
D	0.015	0.021	0.39	0.53		
F	0.040	0.70	1.02	1.77		
G	0.100	BSC	2.54 BSC			
Н	0.050	BSC	1.27 BSC			
J	0.008	0.015	0.21	0.38		
K	0.110	0.130	2.80	3.30		
L	0.295	0.305	7.50	7.74		
M	0°	10 °	0 °	10 °		
S			0.51	1.01		

Notes

Notes

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